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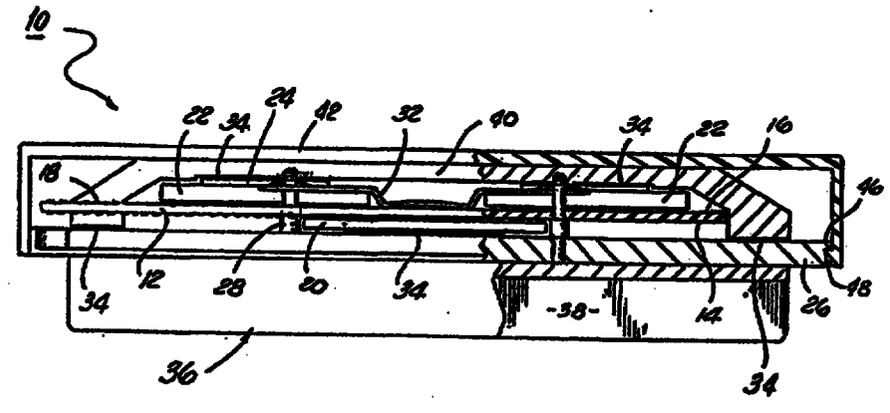
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(54) Title: THERMAL BUS BAR DESIGN FOR AN ELECTRONIC CARTRIDGE



(57) Abstract

One embodiment of the present invention is an electronic assembly (10) which may have a first integrated circuit package (20) mounted to a first side of a substrate (12) and a second integrated circuit package (22) mounted to a second side of the substrate (12). A thermal plate (26) may be thermally coupled to the first integrated circuit package (20). A heat sink (36) may be mounted to the thermal plate (26). A thermal bus bar (40) may be is thermally coupled to the second integrated circuit package (22) and the thermal plate (26). The thermal bus bar (40) allows heat to flow from the second integrated circuit package (22) to the thermal plate (20) and heat sink (36). The electronic assembly (10) of the present invention can thus remove heat from integrated circuit packages located on both sides of a substrate (12) with only one heat sink (36).